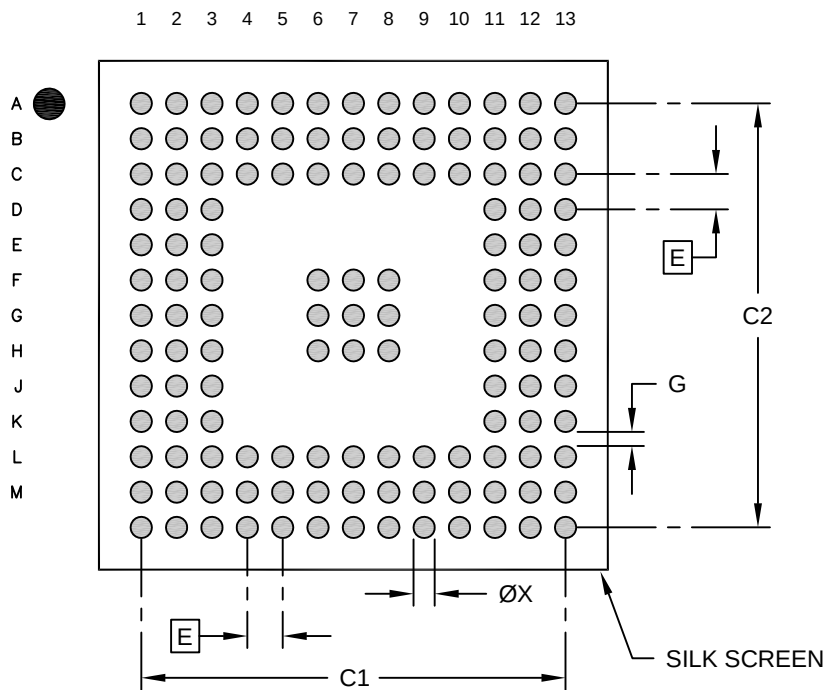


129-Ball Thin Fine Pitch Ball Grid Array (2H) - 7x7 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Overall Contact Pad Spacing	C1		6.00	
Overall Contact Pad Spacing	C2		6.00	
Contact Pad Width (X129)	X1			0.30
Contact Pad to Contact Pad	G	0.20		

Notes:

- 1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.